

a² 10. (Amended) The method of manufacturing electronic parts according to claim 7, wherein a holding jig comprises heat-resistant material having a heat-resistance temperature of about 250°C.

11. The method of manufacturing electronic parts according to claim 7, wherein a holding jig includes a laminate structure of a hard plate and the elastic material.

a³ 15. (New) A method of manufacturing electronic parts according to claim 7, wherein the elastic material is a rubber.

16. (New) A method of manufacturing electronic parts according to claim 7, wherein the elastic material is a laminating material.
